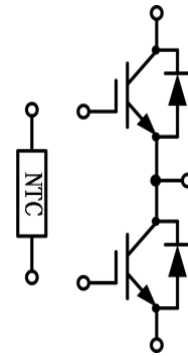
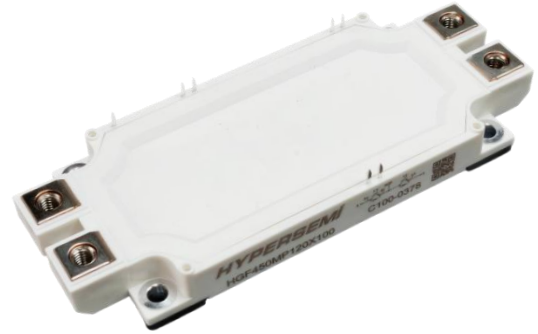


Econodual3 Half Bridge IGBT Module

$V_{CES} = 1200V$, $I_C = 400A$, $V_{CE(sat)} = 1.8V$

Features

- High Short Circuit Capability, Self Limiting Short Circuit Current
- High Current Density
- High surge current capability
- High Power Density
- Integrated NTC temperature sensor



Applications

- Commercial Agriculture Vehicles
- Motor Drives
- Solar Applications
- UPS Systems

IGBT, Inverter Maximum Ratings

Parameter	Symbol	Test Condition	Value	Unit
Collector-emitter voltage	V_{CES}	$T_{vj}=25^{\circ}C$, $V_{GE}=0V$	1200	V
Continuous collector current	I_{CN}	$T_C=100^{\circ}C$, $T_{vj\ max}=175^{\circ}C$	400	A
Repetitive peak collector current	I_{CRM}	$t_P=1ms$, $T_{vj}=25^{\circ}C$	800	A
Gate-emitter peak voltage	V_{GES}	$T_{vj}=25^{\circ}C$	± 30	V
SC data	I_{SC}	$V_{GE} \leq 15V$, $V_{CC}=800V$ $V_{CE\ max}=V_{CES}-L_{Sce} * di/dt$, $t_P \leq 10\mu s$, $T_{vj}=150^{\circ}C$	1600	A
Total power dissipation	P_{tot}	$T_C=25^{\circ}C$, $T_{vj\ max}=175^{\circ}C$	2055 ¹⁾	W

Characteristics Values

Parameter	Symbol	Test Condition	Value			Unit	
			Min.	Typ.	Max.		
Collector-emitter saturation voltage	V_{CEsat}	$I_C=400A$, $V_{GE}=15V$	$T_{vj}=25^{\circ}C$	1.8	2.15	V	
			$T_{vj}=125^{\circ}C$	2.1			
			$T_{vj}=150^{\circ}C$	2.2			
Gate-emitter threshold voltage	V_{GEth}	$I_C=6.4mA$, $V_{CE}=V_{GE}$	$T_{vj}=25^{\circ}C$	5	5.9	6.5	
			$T_{vj}=150^{\circ}C$		4.2		
Gate charge	Q_G	$V_{GE}=-8V/+15V$		4.7		μC	

Integrated gate resistor	R_G	$T_{vj}=25^{\circ}\text{C}$		4.4		Ω	
Input capacitance	C_{ies}	$T_{vj}=25^{\circ}\text{C}$, $f=100\text{kHz}$, $V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$		46.7		nF	
Output capacitance	C_{oes}	$T_{vj}=25^{\circ}\text{C}$, $f=100\text{kHz}$, $V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$		2			
Reverse transfer capacitance	C_{res}	$T_{vj}=25^{\circ}\text{C}$, $f=100\text{kHz}$, $V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$		0.41			
Collector-emitter cut-off current	I_{CES}	$V_{CE}=1200\text{V}$, $V_{GE}=0\text{V}$	$T_{vj}=25^{\circ}\text{C}$		1	mA	
			$T_{vj}=150^{\circ}\text{C}$		4		
Gate-emitter leakage current	I_{GES}	$V_{CE}=0\text{V}$, $V_{GE}=20\text{V}$, $T_{vj}=25^{\circ}\text{C}$			400	nA	
Turn-on delay time	t_{don}	$I_C=400\text{A}$, $V_{CE}=600\text{V}$, $V_{GE}=-8\text{V}/+15\text{V}$, $R_{Gon}=1.4\Omega$, $R_{Goff}=12.9\Omega$, Inductive Load	$T_{vj}=25^{\circ}\text{C}$	0.36		μs	
			$T_{vj}=125^{\circ}\text{C}$	0.38			
			$T_{vj}=150^{\circ}\text{C}$	0.38			
Rise time	t_r		$T_{vj}=25^{\circ}\text{C}$	0.09			
			$T_{vj}=125^{\circ}\text{C}$	0.09			
			$T_{vj}=150^{\circ}\text{C}$	0.1			
Turn-off delay time	t_{doff}		$T_{vj}=25^{\circ}\text{C}$	2.5			
			$T_{vj}=125^{\circ}\text{C}$	2.7			
			$T_{vj}=150^{\circ}\text{C}$	2.7			
Fall time	t_f	$T_{vj}=25^{\circ}\text{C}$	1.54				
		$T_{vj}=125^{\circ}\text{C}$	1.2				
		$T_{vj}=150^{\circ}\text{C}$	1.29				
Turn-on energy loss per pulse	E_{on}	$I_C=400\text{A}$, $V_{CE}=600\text{V}$, $V_{GE}=-8\text{V}/+15\text{V}$, $R_{Gon}=1.4\Omega$, $R_{Goff}=12.9\Omega$, $L_s=35\text{nH}$, $di/dt=4600\text{A}/\mu\text{s}$ ($T_{vj}=150^{\circ}\text{C}$), $du/dt=2000\text{V}/\mu\text{s}$ ($T_{vj}=150^{\circ}\text{C}$)	$T_{vj}=25^{\circ}\text{C}$	17.9		mJ	
			$T_{vj}=125^{\circ}\text{C}$	25.4			
			$T_{vj}=150^{\circ}\text{C}$	35			
Turn-off energy loss per pulse	E_{off}		$T_{vj}=25^{\circ}\text{C}$	91.2			
			$T_{vj}=125^{\circ}\text{C}$	95.8			
			$T_{vj}=150^{\circ}\text{C}$	99.9			
Thermal resistance, junction to case	R_{thJC}		per IGBT			0.073	K/W

Diode, Inverter Maximum Ratings

Parameter	Symbol	Test Condition	Value	Unit	
Repetitive peak reverse voltage	V_{RRM}	$T_{vj}=25^{\circ}\text{C}$	1200	V	
Continuous forward current	I_{FN}	$T_C=100^{\circ}\text{C}$, $T_{vj\max}=175^{\circ}\text{C}$	400	A	
Maximum repetitive forward current	I_{FRM}	$t_p=1\text{ms}$	800	A	
ft-value	I^2t	$V_R=0\text{V}$, $t_p=10\text{ms}$	$T_{vj}=125^{\circ}\text{C}$	35600	A ² s
			$T_{vj}=150^{\circ}\text{C}$	28000	

Characteristics Values

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward voltage	V _F	I _F =400A, V _{GE} =0V	T _{Vj} =25°C	2.04		V
			T _{Vj} =125°C	2.11		
			T _{Vj} =150°C	2.08		
Peak reverse recovery current	I _{RM}		T _{Vj} =25°C	300		A
			T _{Vj} =125°C	338		
			T _{Vj} =150°C	357		
Recovered charge	Q _r	I _F =400A, V _R =600V, V _{GE} =-8V, diF/dt=6000A/μs (T _{Vj} =150°C)	T _{Vj} =25°C	36.4		μC
			T _{Vj} =125°C	57		
			T _{Vj} =150°C	64		
Reverse recovery energy	E _{rec}		T _{Vj} =25°C	18.2		mJ
			T _{Vj} =125°C	26.9		
			T _{Vj} =150°C	30.2		
Thermal resistance, junction to case	R _{thJC}	per FRD			0.116	K/W

NTC-Thermistor

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Rated resistance	R ₂₅	T _C =25°C		5.0		kΩ
Deviation of R ₁₀₀	ΔR/R	T _C =100°C, R ₁₀₀ =493Ω	-3		3	%
Power dissipation	P ₂₅	T _C =25°C			60	mW
B-value	B _{25/50}	$R_2=R_{25} \exp[B_{25/50}(1/T_2-1/(298.15K))]$		3375		K
B-value	B _{25/80}	$R_2=R_{25} \exp[B_{25/80}(1/T_2-1/(298.15K))]$		3411		K
B-value	B _{25/100}	$R_2=R_{25} \exp[B_{25/100}(1/T_2-1/(298.15K))]$		3433		K

Characteristics Values(Module)

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Maximum junction temperature	T _{Vj max}	-			175	°C
Temperature under switching conditions	T _{Vj op}	-	-40		150	°C
Storage temperature	T _{stg}	-	-40		125	°C
Stray inductance module	L _{sCE}	-		22		nH
Module lead resistance, terminals-chip	R _{CC'+EE'}	T _{Vj} =25°C, per switch		1		mΩ
Isolation test voltage	V _{ISOL}	R _{MS} , f=50Hz, t=1min		2.5		kV

Creepage distance	ds	Terminal to heatsink	14.5	mm		
		Terminal to terminal	13	mm		
Clearance distance	da	Terminal to heatsink	12.5	mm		
		Terminal to terminal	10	mm		
Comperative tracking index	CTI	-	>200	-		
Mounting torque for module mounting	M1	Screw M5	3	-	6	N·m
Terminal connection torque	M2	Screw M6	3	-	6	N·m
Internal isolation	-	Basic insulation (class1, IEC 61140)	Al ₂ O ₃		-	
Material of module base plate	-	-	Cu+Ni		-	
Dimensions	LxWxH	-	152.1x62x20.8		mm	
Weight	G	-	338		g	

Typical Characteristics

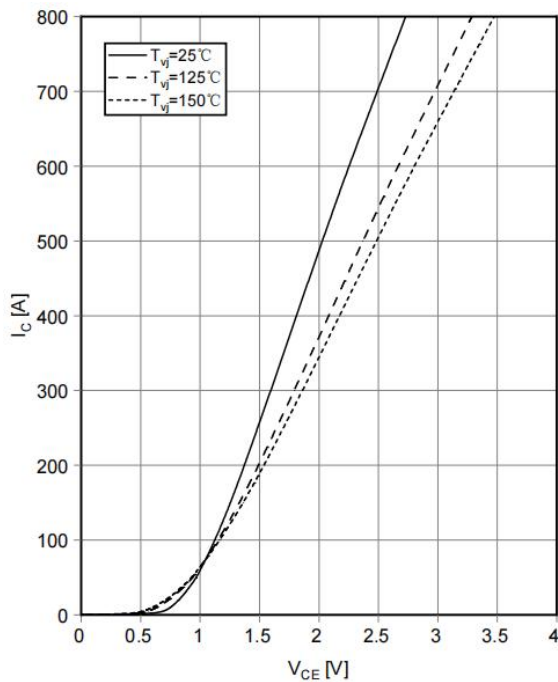


Fig 1. Output characteristic IGBT, Inverter(typical)
 $I_c=f(V_{CE}), V_{GE}=15V$

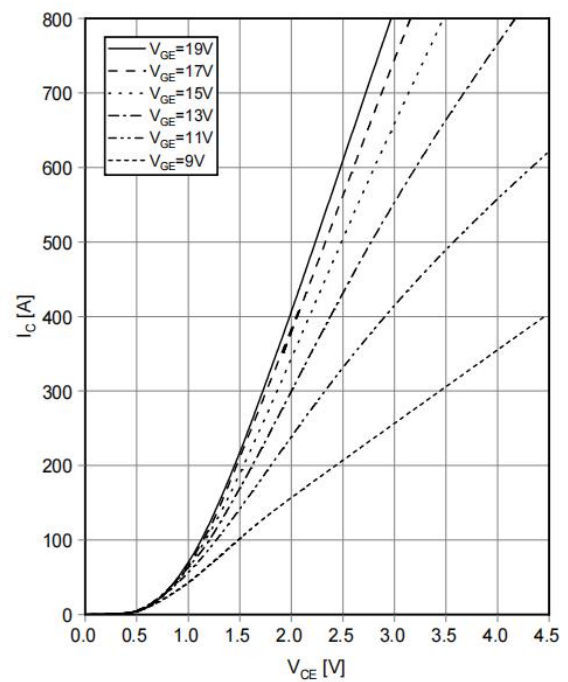


Fig 2. Output characteristic IGBT, Inverter(typical)
 $I_c=f(V_{CE}), T_{vj}=150^{\circ}C$

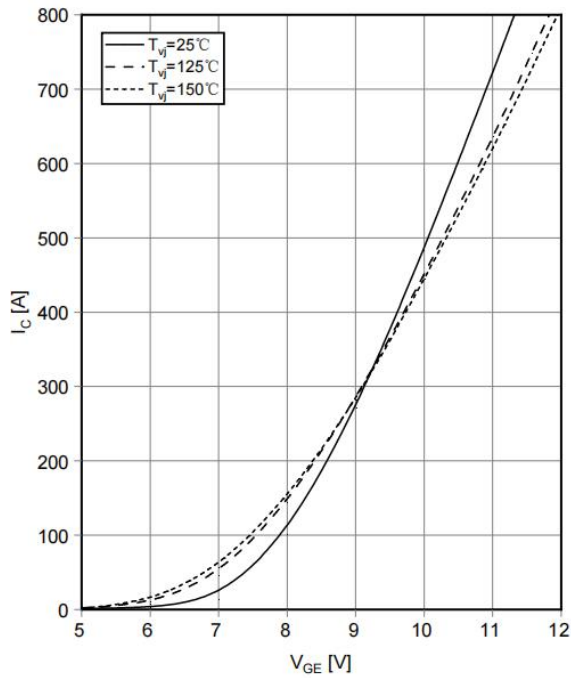


Fig 3. Transfer characteristic IGBT, Inverter(typical)
 $I_c = f(V_{GE})$, $V_{CE} = 20V$

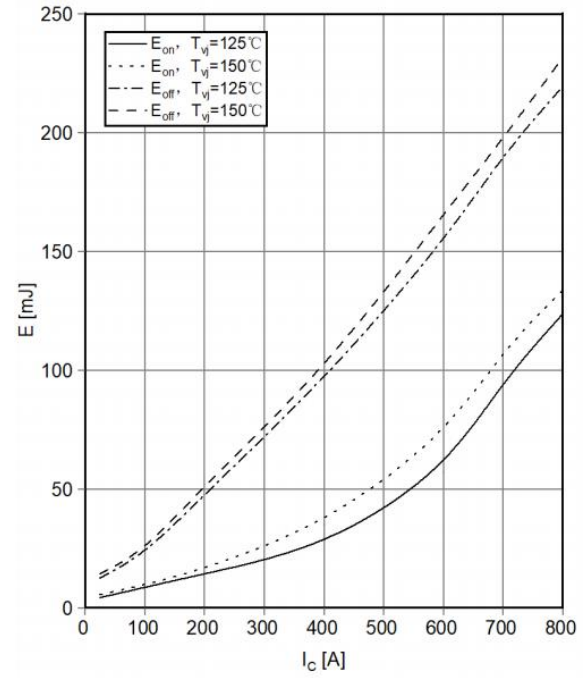


Fig 4. Switching losses IGBT, Inverter(typical)
 $E_{on} = f(I_c)$, $E_{off} = f(I_c)$, $V_{GE} = 15V$, $R_{Gon} = 1.4\Omega$, $R_{Goff} = 12.9\Omega$,
 $V_{CE} = 600V$

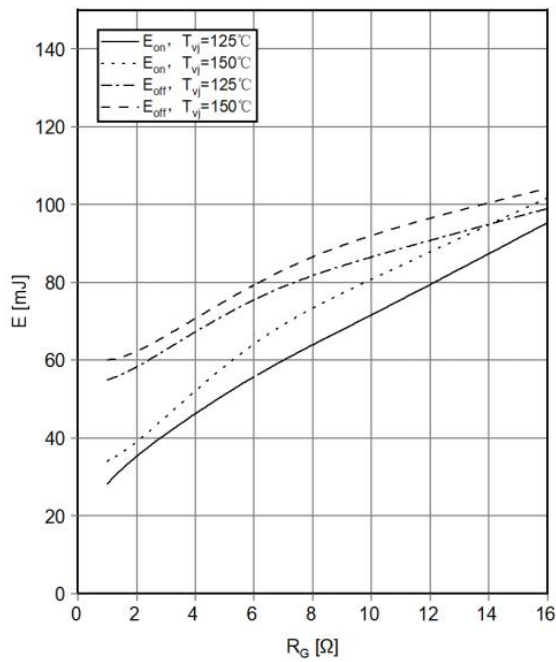


Fig 5. Switching losses IGBT, Inverter(typical)
 $E_{on} = f(R_G)$, $E_{off} = f(R_G)$, $V_{GE} = -8/+15V$, $I_c = 400A$, $V_{CE} = 600V$

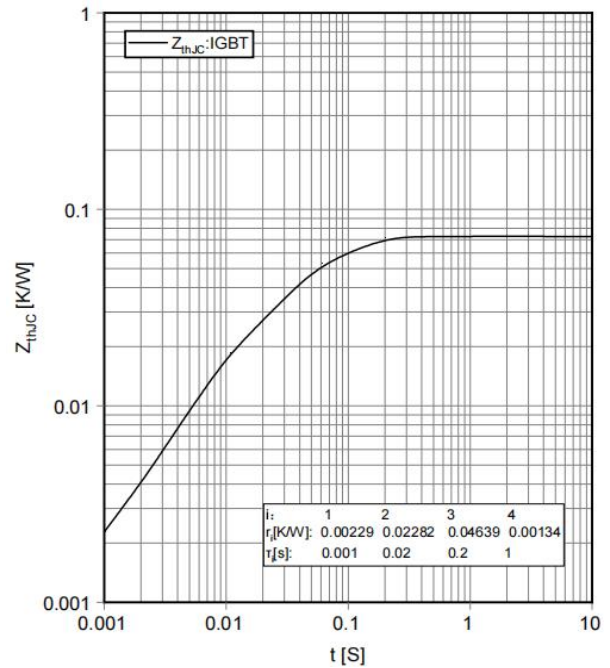


Fig 6. Transient thermal impedance IGBT, Inverter $Z_{thJc} = f(t)$

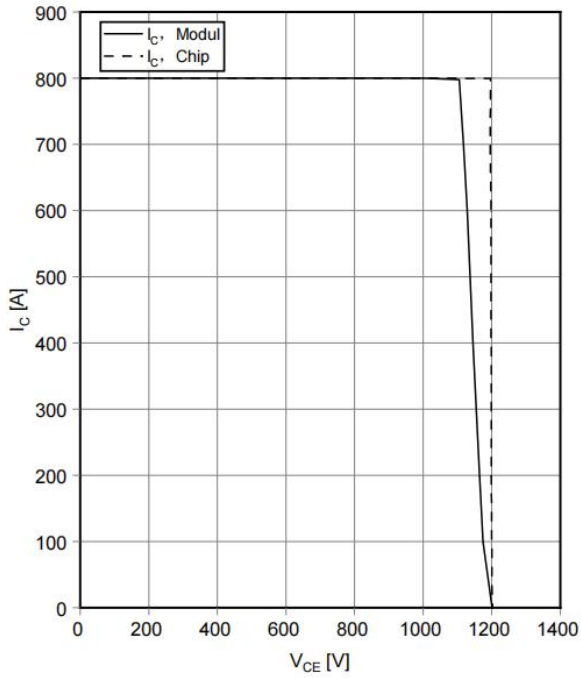


Fig 7. Reverse bias safe operating area IGBT, Inverter(RBSOA)
 $I_c=f(V_{CE})$, $V_{GE}=15V$, $R_{Goff}=2\Omega$, $T_{vj}=150^\circ C$

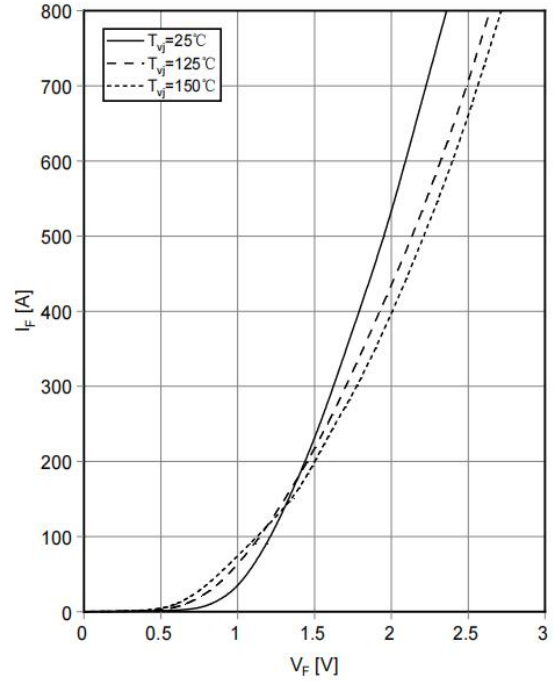


Fig 8. Forward characteristic of FRD, Inverter(typical)
 $I_F=f(V_F)$

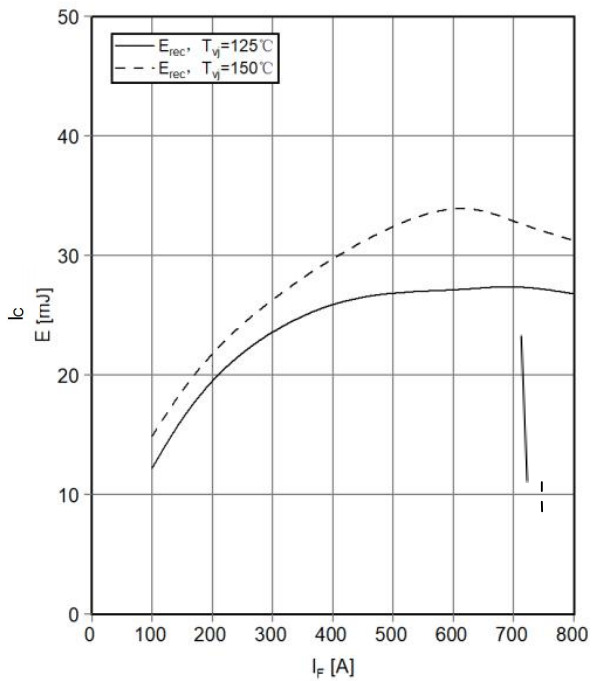


Fig 9. Transient thermal impedance FRD, Inverter
 $E_{rec}=f(I_F)$, $R_{Gon}=1.4\Omega$, $V_{CE}=600V$

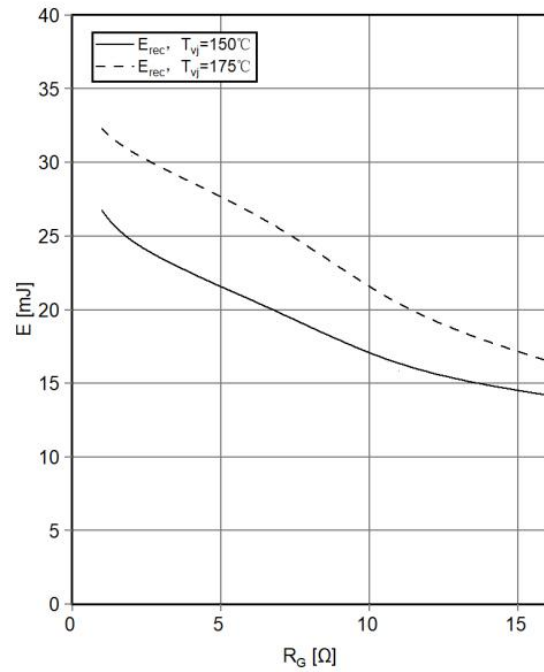


Fig 10. NTC-Thermistor-temperature characteristic
 $E_{rec}=f(R_G)$, $I_F=400A$, $V_{CE}=600V$

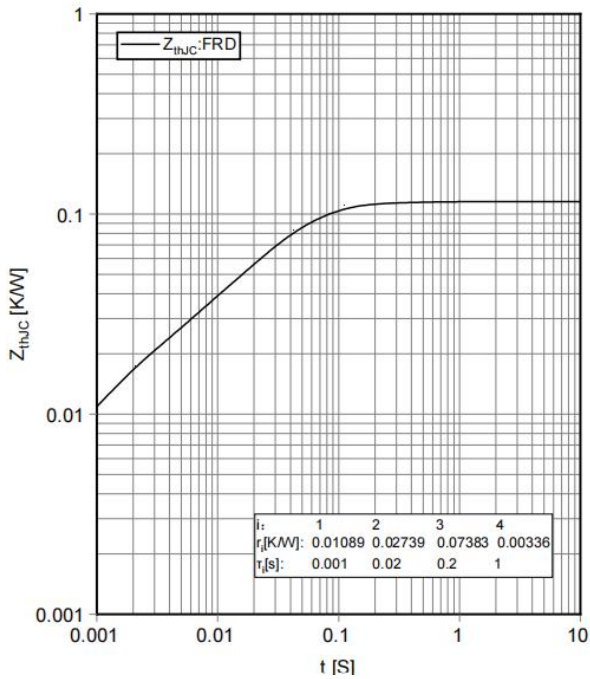


Fig 11. Transient thermal impedance FRD, Inverter
 $Z_{thJC}=f(t)$

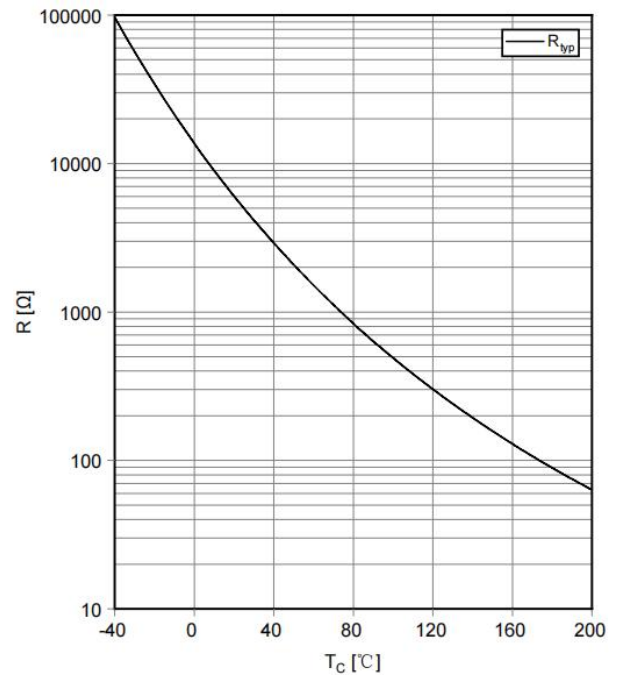


Fig 12. NTC-Thermistor-temperature characteristic
 $R=f(T)$

Circuit Diagram

